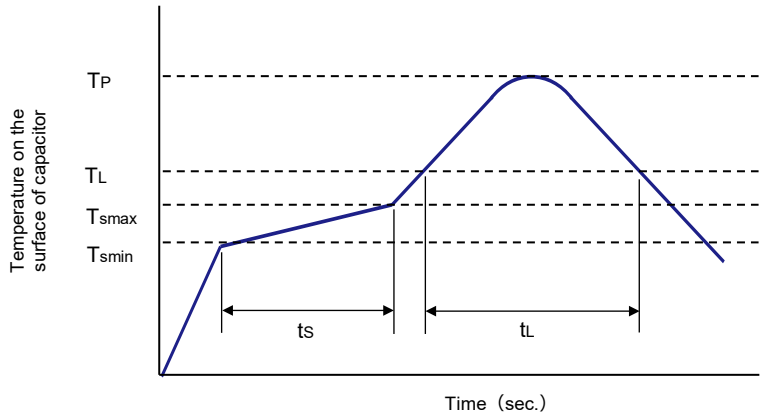
Mounting specifications

◇ Recommendable reflow soldering (SMD type)



Reflow soldering		Condition A	Condition B	Condition C
		Peak temperature 260 °C lead free soldering profile	Peak temperature 250 °C lead free soldering profile	Peak temperature 250 °C lead free soldering profile (SVPG, SVPF, SVF, SVPK, SXV)
Peak temperature (TP)		260 ℃	250 ℃	250 ℃
Soldering time (tL) above soldering temperature (TL)	TL ≧ 245 ℃	–		30 seconds max.
	TL ≧ 230 ℃	40 seconds max.		–
	TL ≧ 220 ℃	50 seconds max.		–
	TL ≧ 217 ℃	–		90 seconds max.
	TL ≧ 200 ℃	60 seconds max.		–
Preheat	Temperature max. (Tsmax)	180 ℃		200 ℃*1
	Temperature min. (Tsmin)	150 ℃		
	Time (ts) from (Tsmin) to (Tsmax)	120 seconds max.		
The cycles of reflow soldering		1 times	2 times	2 times

*1 SXV series : 180℃

◇ Flow soldering (Radial lead type)

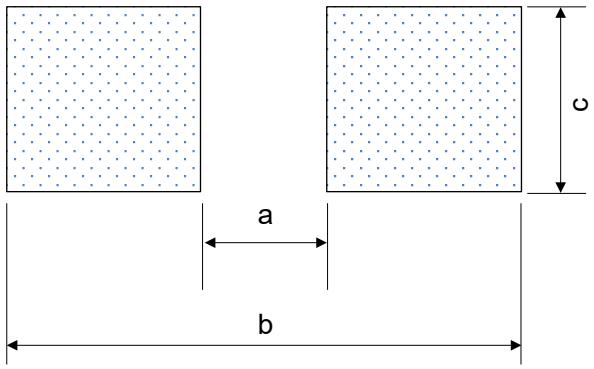
	Temperature	Time	Flow number
Preheating	120 ℃ or less (ambient temperature)	120 sec. or less	1 time
Soldering condition	260 ℃+5 ℃ or less	10+1 sec. or less	2 times or less*1

*1 : When soldering 2 times, total immersion time should be 10+1 sec. or less.

◇ Soldering with a soldering iron

Tip of a soldering iron : 400 ℃±10 ℃
Working time : 5 sec. max.

Land Pattern



Unit : mm

Size code	a	b	c
A5	1.0	6.2	1.6
B45	1.4	7.4	1.6
B6	1.4	7.4	1.6
C5	2.1	9.1	1.6
C55	2.1	9.1	1.6
C6	2.1	9.1	1.6
C65	2.1	9.1	1.6
C8	2.1	9.1	1.6
C10	2.1	9.1	1.6
C10L	2.1	9.1	2.5
E7	2.8	11.1	1.9
E10	2.8	11.1	1.9
E12	2.8	11.1	1.9
F8	4.3	13.1	1.9
F10	4.3	13.1	1.9
F12	4.3	13.1	1.9